



04-18-2003



102423381

Docket No.: HSC27

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

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To the Honorable Commissioner of Patent

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Terence Lee Horstman

2. Name and address of receiving party(ies):

Name: Hemlock Semiconductor Corporation

Address: 12334 Geddes Road

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

City: Hemlock

State/Prov.: MI

Country: US

ZIP: 48626

Execution Date: April 2, 2003

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.

Filing date

B. Patent No.(s)

10/27,362

August 22, 2002

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Catherine U. Brown

Registration No. 44,565 - (989) 496-1725

Address:



00137

PATENT TRADEMARK OFFICE

City: _____ State/Prov.: _____

Country: _____ ZIP: _____

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☒ Authorized to be charged to deposit account

8. Deposit account number:

04-1520

(Attach duplicate copy of this page if paying by deposit account)

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Catherine U. Brown

Name of Person Signing

Signature

Date

3

Total number of pages including cover sheet, attachments, and

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

PATENT

REEL: 013959 FRAME: 0831

10227362

04/17/2003 LHELLER 41580

01 FC-0021

ASSIGNMENT

WHEREAS We, Terence Lee Horstman of Frankenmuth, County of Saginaw, and State of Michigan has co-invented certain new and useful improvements in

METHOD AND APPARATUS FOR IMPROVING SILICON PROCESSING EFFICIENCY

for which application for United States Letters Patent has been executed by me on April , 2003 and

WHEREAS, the Hemlock Semiconductor Corporation, a corporation organized and existing under the Laws of the State of Michigan, having its principal place of business at Hemlock, Michigan, U.S.A., is desirous of acquiring the said invention and said application and any and all Letters Patent that may be obtained therefore or thereupon, and all reissues and extensions thereof;

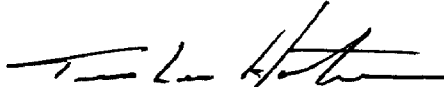
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of the sum of One Dollar (\$1.00), and other good and valuable considerations, to me in hand paid by the said Hemlock Semiconductor Corporation, the receipt of which is hereby acknowledged, I have sold, assigned, transferred and set over and by these presents do sell, assign, transfer and set over unto the said Hemlock Semiconductor Corporation, its successors, and assigns, the full and exclusive right, title and interest in and to the said invention and said application for Letters Patent of the United States therefore, and in and to any Divisions and Continuations thereof and in and to any and all United States Letters Patent and reissues and extensions thereof that may be issued for the said invention, to have and to hold for its own use and behoof and the use and behoof of its successors and assigns as fully and entirely as the same might be enjoyed by us if this sale and assignment had not been made; and

HEREBY AUTHORIZE and request the Commissioner of Patents and Trademarks to issue the said Letters Patent and any reissues and extensions thereof to the said Hemlock Semiconductor Corporation as assigns of the entire right, title and interest in and to the said invention and said application and Letters Patent issued therefore or thereupon; and

HEREBY AGREE to execute all instruments and documents within my power which may be necessary for the carrying out of this assignment in full; and to execute any divisional or continuing application or applications which may be necessary or proper to obtain full protection on the invention hereby assigned; and to execute any and all supplemental oaths and preliminary statements should the same be proper and necessary in the prosecution of the aforesaid applications; and

HEREBY FURTHER ASSIGN unto the said Hemlock Semiconductor Corporation, its successors, and assigns, the whole right, title and interest in and to the invention disclosed in the said application throughout all countries foreign to the United States, and do hereby ratify any acts of the said Hemlock Semiconductor Corporation, its successors and assigns, in applying for patents therefore in its own name in countries where such procedure is proper and do agree to execute applications for said invention in the several countries where it is necessary that the same be executed by the inventors, and to execute assignments of such applications and the patents to be obtained therefore to the said Hemlock Semiconductor Corporation, its successors and assigns.

IN WITNESS WHEREOF I have hereunto set my hand and affixed my seal this
4TH day of April, 2003.

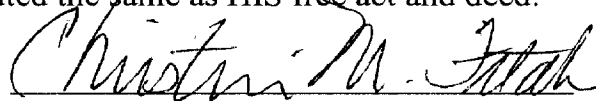


Terence Lee Horstman

STATE OF Michigan)
) SS,
 COUNTY OF Bay)

On this 4TH day of April, 2003, before me personally appeared Terence Lee Horstman to me known to be the person described in and who executed the foregoing instrument and acknowledged that HE executed the same as HIS free act and deed.

Christine M. Filak
 Notary Public, Midland County, Michigan
 My Commission Expires April 30, 2007
 Acting In BAY COUNTY


 Notary Public